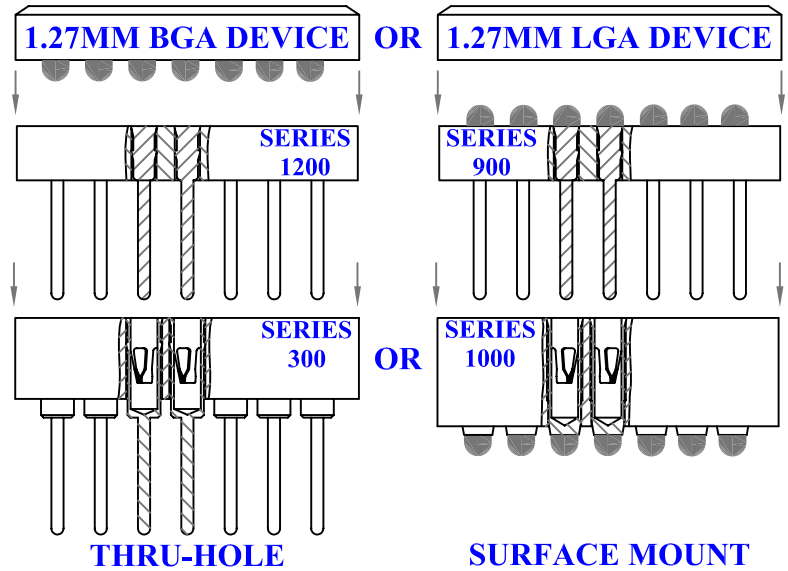
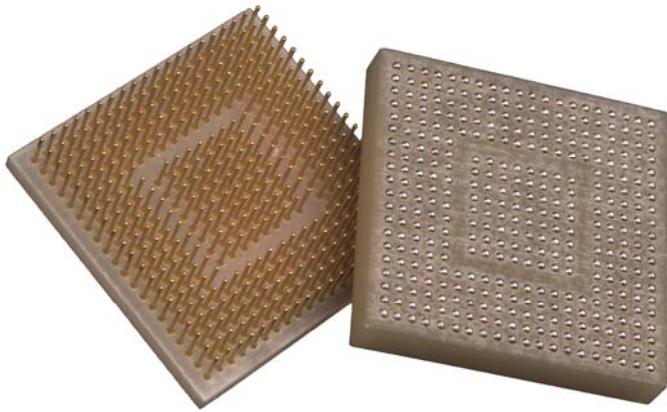


# BALL GRID ARRAY SOCKET SYSTEM for .050 [1.27 MM] ADAPTERS



**Thermal Performance (STANDARD FR-4):**

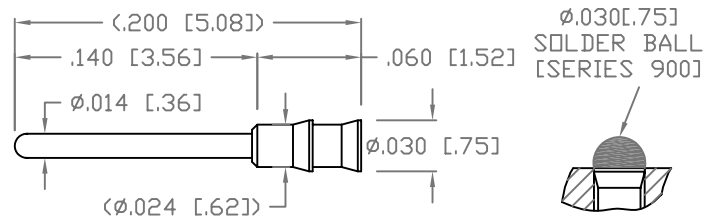
Operating Temperature [range] (To):	-55° to 140° C
Glass Transition Temperature [range] (Tg) :	150° to 200° C
Resistance to Soldering Heat [Thermal Stress]:	10 seconds @ 288° C
Flammability rating:	UL94V-0
IEC Climatic Category:	55 / 125 / 21
Autoclaveable	

**Electrical Performance: Tests IAW MIL-STD-202 OR -1344 Methods.**

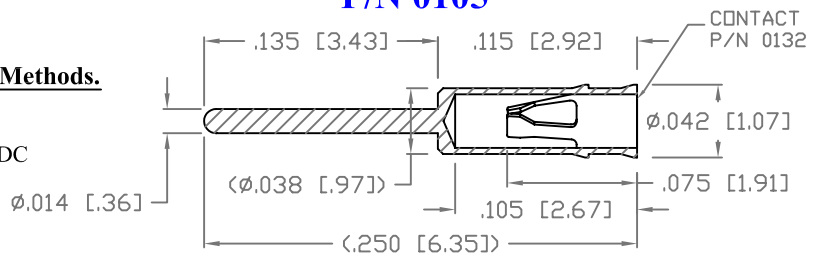
Maximum Voltage:	50 VAC / 60 VDC
Maximum Current:	3 Ampere per contact
Contact Resistance: Dry Circuit:	10 mohms Max. @ 10 ma / 5 VDC
Insulation Resistance, @500VDC:	5,000 MegOhms Min.
Dielectric Withstanding Voltage:	500 VAC Min.
Capacitance:	1 pf (PicoFarads) Max.
Self Inductance:	2 nH (NanoHenrys) Max.

**Contact Materials & Finishes (Other finishes available):**

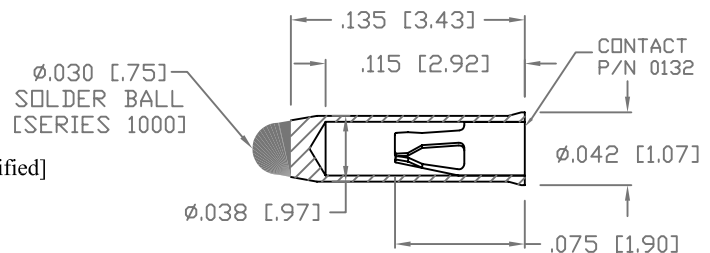
Bodies:	Brass Alloy C36000 per ASTM-B16, Plated Gold, 10 uIn Min. over Nickel, 100uIn Min. [ or ] Tin, 200 uIn. Min. over Nickel, 100 uIn Min.
Clips:	Beryllium Copper Alloy C17200 per ASTM-B194 Plated 10uIn Min. Gold over 50uIn Min. Nickel
Solder Balls:	63/37 [Sn/Pb] Eutectic Solder, Ø.020 or Ø.030 [User Specified] Melting Temperature 183°C[361°F]



**P/N 0105**



**P/N 0107**



**P/N 0106**

**PART NUMBER / ORDER INFORMATION:**

**1200 - 49 F - 0105 - 07A2**  
 PRODUCT CODE      PIN COUNT      MATERIAL      CONTACT P/N      PATTERN CODE

300 = SOCKET, PIN GRID ARRAY [PGA]	
900 = LGA INTERPOSER [PGA]	
1000 = SOCKET, BGA [SBGA]	
1200 = BGA INTERPOSER [PBGA]	

A = ACRYLIC
E = PEEK [POLYETHERETHERKETONE]
H = POLYIMIDE, [MIL-L-13949/10]
F = FR-4, [IPC-4101/24]
R = RYTON [POLYPHENYLENE SULFIDE]
U = G.E. ULTEM [POLYETHERIMIDE]

**01A1 - 99Z9  
OVER 24,000  
PATTERNS  
AVAILABLE**